



DSPACK 2

Features:

- Isolated mounting base 4000V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving
- UL Recognized

Typical Applications

- AC/DC Motor drives
- Various rectifiers
- DC supply for PWM inverter

| V_{DSM}, V_{RSM} | V_{DRM}, V_{RRM} | Type & Outline |
|--------------------|--------------------|----------------|
| 2700V | 2600V | DSKT 135/26 |
| 2900V | 2800V | DSKT 135/28 |
| 3100V | 3000V | DSKT 135/30 |
| 3300V | 3200V | DSKT 135/32 |
| 3500V | 3400V | DSKT 135/34 |
| 3700V | 3600V | DSKT 135/36 |

| SYMBOL | CHARACTERISTIC | TEST CONDITIONS | $T_j(^{\circ}C)$ | VALUE | | | UNIT |
|------------------------|--|--|------------------|-------|------|-------|-------------------|
| | | | | Min | Type | Max | |
| $I_{T(AV)}$ | Mean on-state current | 180° half sine wave 50Hz Single side cooled, $T_c=85^{\circ}C$ | 125 | | | 135 | A |
| $I_{T(RMS)}$ | RMS on-state current | | 125 | | | 212 | A |
| I_{DRM} I_{RRM} | Repetitive peak current | at V_{DRM} at V_{RRM} | 125 | | | 25 | mA |
| I_{TSM} | Surge on-state current | 10ms half sine wave $V_R=60\%V_{RRM}$ | 125 | | | 3.60 | KA |
| I^2t | I^2t for fusing coordination | | | | | 65 | $A^2s \cdot 10^3$ |
| V_{TO} | Threshold voltage | | 125 | | | 0.94 | V |
| r_T | On-state slope resistance | | | | | 2.40 | mΩ |
| V_{TM} | Peak on-state voltage | $I_{TM}=410A$ | 25 | | | 2.35 | V |
| dv/dt | Critical rate of rise of off-state voltage | $V_{DM}=67\%V_{DRM}$ | 125 | | | 800 | V/μs |
| di/dt | Critical rate of rise of on-state current | $I_{TM}=270A$, Gate source 1.5A $t_r \leq 0.5\mu s$ Repetitive | 125 | | | 100 | A/μs |
| I_{GT} | Gate trigger current | | 25 | 30 | | 150 | mA |
| V_{GT} | Gate trigger voltage | $V_A=12V, I_A=1A$ | | 0.8 | | 2.5 | V |
| I_H | Holding current | | | 20 | | 150 | mA |
| V_{GD} | Non-trigger gate voltage | $V_{DM}=67\%V_{DRM}$ | 125 | 0.2 | | | V |
| $R_{th(j-c)}$ | Thermal resistance Junction to case | Single side cooled per chip | | | | 0.170 | $^{\circ}C/W$ |
| $R_{th(c-h)}$ | Thermal resistance case to heat sink | Single side cooled per chip | | | | 0.08 | $^{\circ}C/W$ |
| V_{iso} | Isolation voltage | 50Hz, R.M.S, $t=1min, I_{iso}: 1mA(MAX)$ | | 4000 | | | V |
| F_m | Thermal connection torque (M6) | | | | 6.0 | | N·m |
| | Mounting torque (M6) | | | | 6.0 | | N·m |
| T_{stg} | Stored temperature | | | -40 | | 125 | $^{\circ}C$ |
| W_t | Weight | | | | 305 | | g |
| Outline | DSPACK 2 | | | | | | |

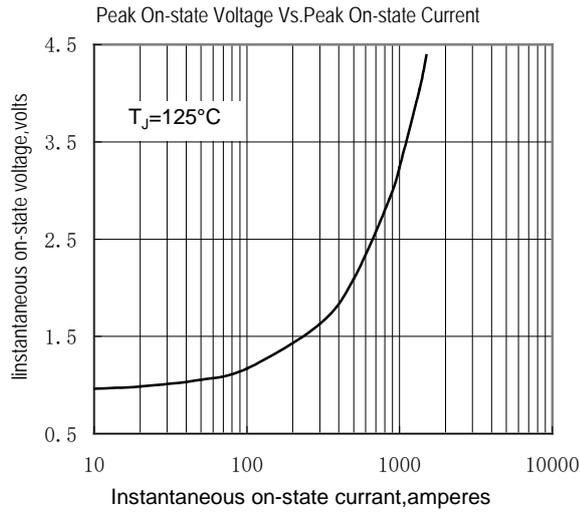


Fig.1

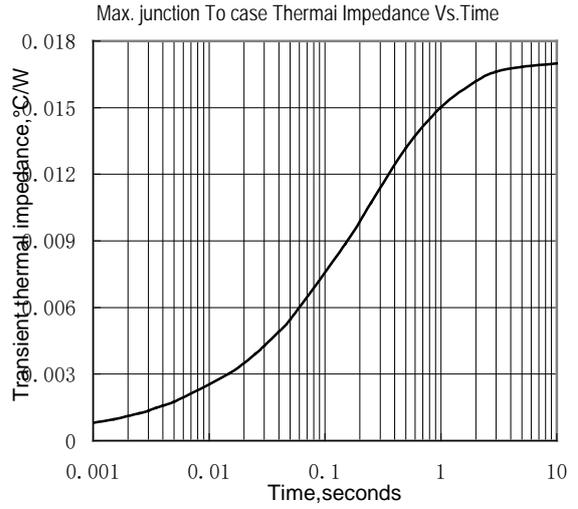


Fig.2

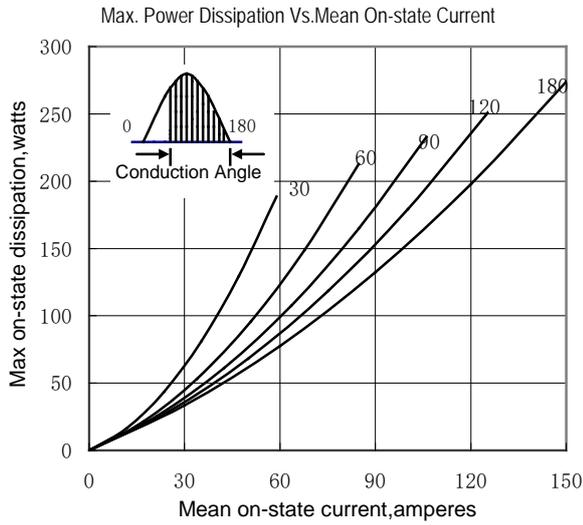


Fig.3

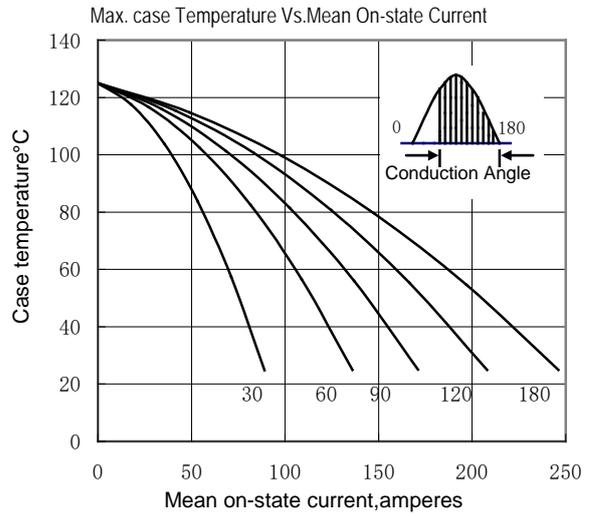


Fig.4

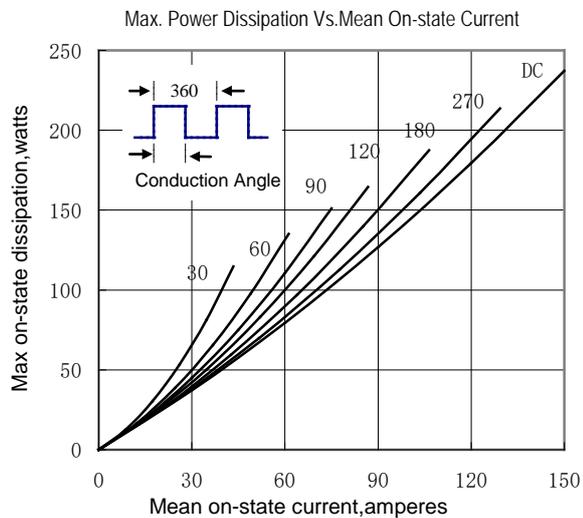


Fig.5

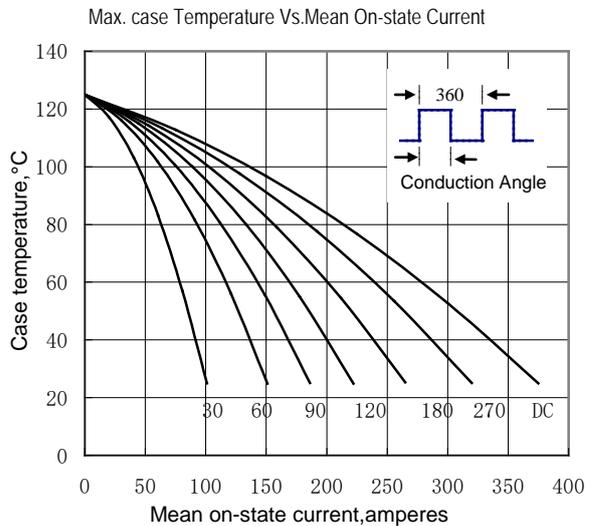


Fig.6

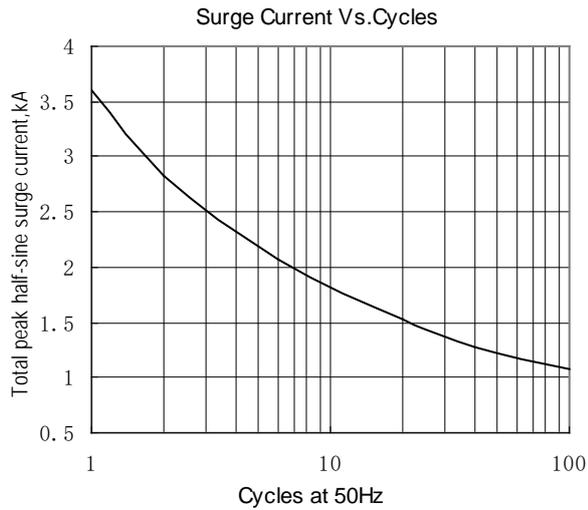


Fig.7

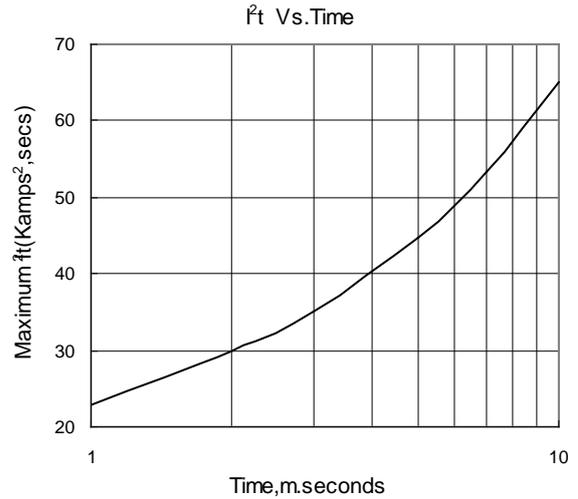


Fig.8

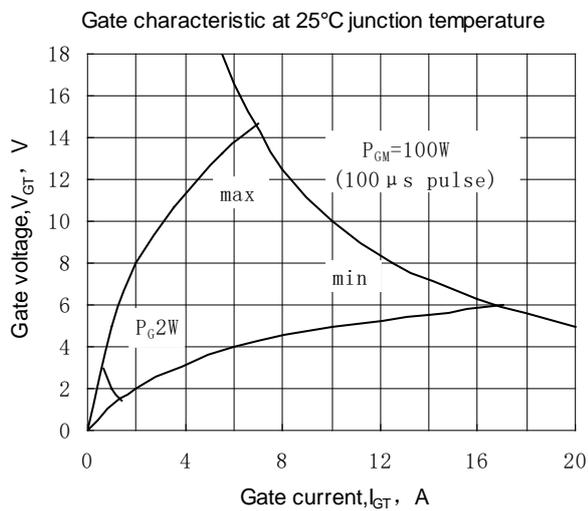


Fig.9

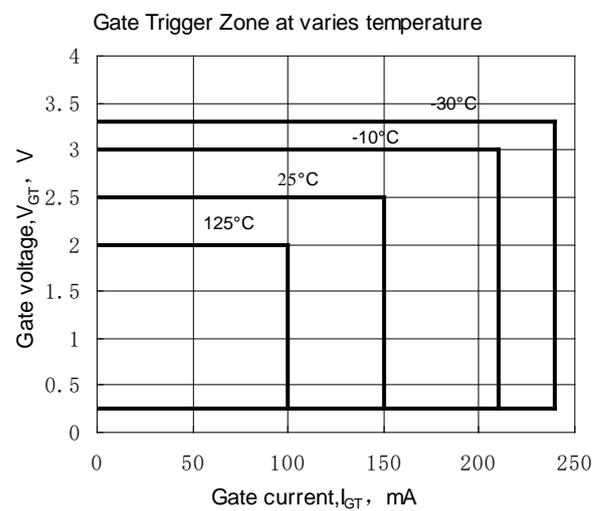


Fig.10

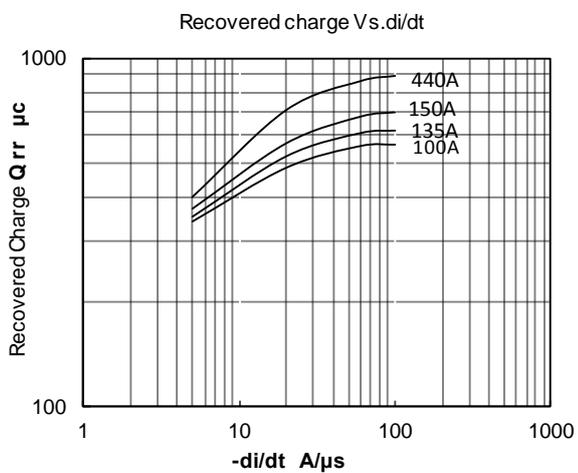


Fig.11

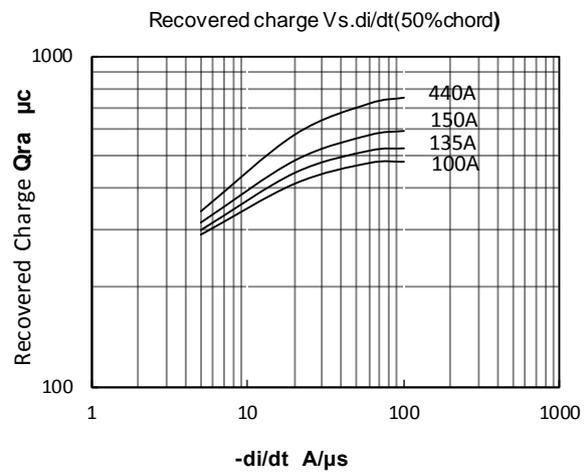


Fig.12

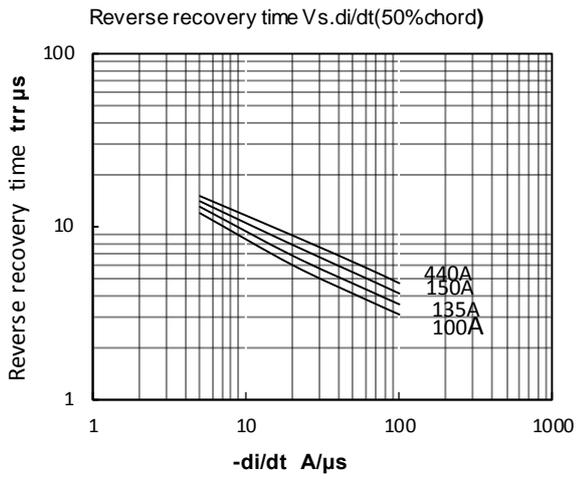


Fig.13

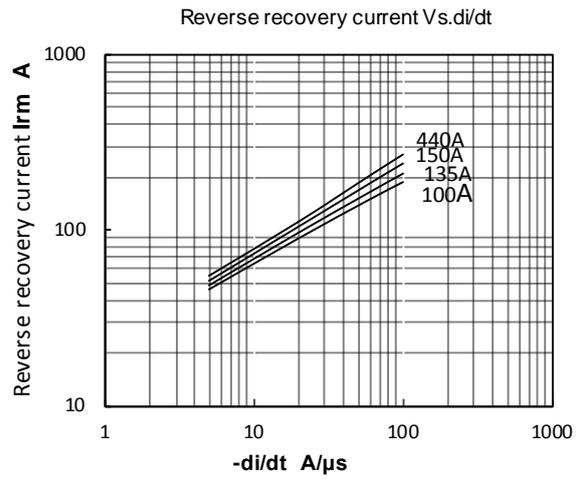
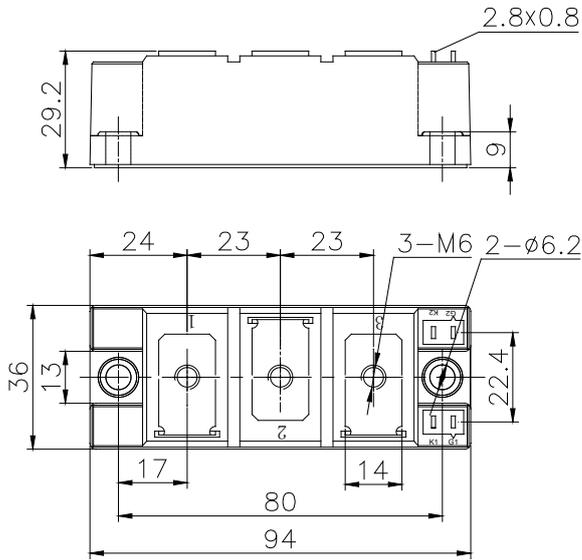
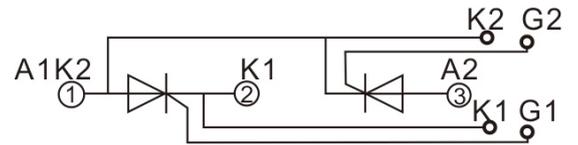


Fig.14

Outline:



DSPACK 2



DSKT